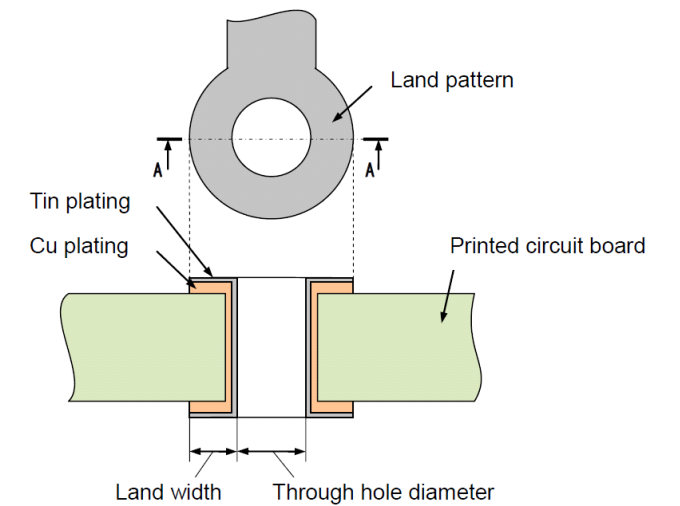
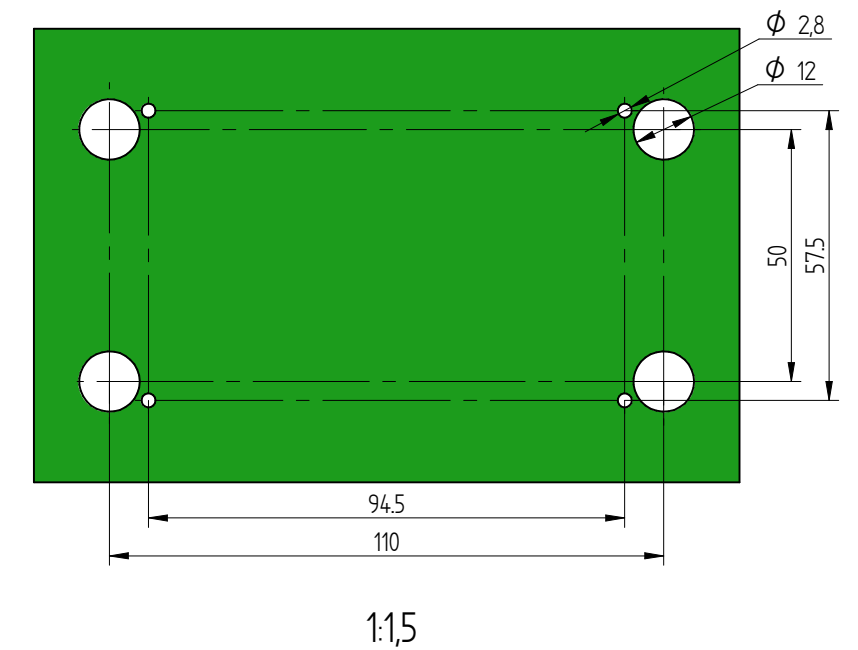


### Specifications for Printed Circuit Boards

1. PCB thickness must not be less than 1.6 mm
2. PCB material should comply with IEC 61249-2-7, double sided or multilayer
3. Both sides of the PCB should be covered with solder mask
4. Plated through-hole specifications for Press-fit pins:
  - Plated hole final diameter:  $\varnothing 2.2 \text{ mm} + 0.09 \text{ mm} / 0.06 \text{ mm}$
  - Thickness of the Cu PTH wall > 25  $\mu\text{m}$  Cu
  - Minimum Cu land width > 0.4 mm
  - Through hole position accuracy:  $\pm 0.1 \text{ mm}$
  - Chemical Tin (Sn) plating: 0.5  $\mu\text{m}$  to 10  $\mu\text{m}$
  - HAL Tin (Sn) plating: 0.5  $\mu\text{m}$  to 50  $\mu\text{m}$
  - Chemical Gold (Au), Silver (Ag) and Organic Solderability Preservative (OSP) are not generally released
  - Minimum distance between the centre of the pin hole and the edge of the PCB or components on the PCB: 4 mm
  - For additional requirements the IEC 60352-5 standard should be considered



### 5. Hole and cutout sizes on the driver PCB



- A. Tolerance of pin positions  $\pm 0.2 \text{ mm}$  at the end of pins
- B. Refer to the module datasheet for pinout and 3D-CAD model
- C. Mounting parameters see in the actual Handling Instructions

02	06.09.2018	Added Press-fit variant	Géczy M.	Buza M.	Package Drawing	View scale 1:1		
01	25.02.2017	Initial Release	Géczy M.	Gyimóthy Zs.				
Rev.	Date	Alteration	Designed	Approved				
General tolerances ISO 2768 - m , K			Ps A3			Page 1/1		
Linear dimensions		$x < 0.5 \pm 0.05$	$0.5 \leq x < 6 \pm 0.1$	$6 \leq x < 30 \pm 0.2$			$30 \leq x < 120 \pm 0.3$	$120 < x \pm 0.5$
Chamfers, radii		$x < 0.3 \pm 0.05$	$0.3 \leq x < 0.5 \pm 0.1$	$0.5 \leq x < 3 \pm 0.2$			$3 \leq x < 6 \pm 0.5$	$6 < x \pm 1$
References		Inspectional dim:	Revision number (Rev.): *				IP Development	Drawing alteration in revision: {}